1/2				CODE NO.	E ELECTRIC CO., LTD.	HIROSE
	9	H36W-**S-0. 3SHW (50)	卫	PART NO.	SPECIFICATION SHEET	HCS SPE
	-06	ELC4-158578-06	DRAWING NO.	DRAW	AT:Assurance Test X:Applicable Test	Note QT:Qualification Test /
2. 19	09. 12. 19	HK. OSHIKIRI	DRAWN		ed, refer to JIS C 5402.	Unless otherwise specified, refer to JIS C
2. 22	09. 12. 22		DESIGNED			
2. 24	09. 12. 24	ED RI. TAKAYASU  D FN. TAMURA	APPROVED CHECKED			REMARK
Ħ	DATE	CHECKED		DESIGNED	DESCRIPTION OF REVISIONS	COUNT DESC
		CRACK AND LOOSENESS	ÎШ	<u> </u>		
		③ INSULATION RESISTANCE: 50 M $\Omega$ MIN. (AT DRY)	(AT DRY)	<u> </u>		
I	×	CONTACT RESISTANCE: 100 mΩ MAX. INSULATION RESISTANCE: 1 MΩ MIN. (AT HIGH HUMIDITY)	INSULATION RESISTANCE:  (AT HIGH HUMIDITY		EXPOSED AI -10 IO +65°C, RELATIVE HUMIDITY 90 TO 96%, 10 CYCLES,TOTAL 240 h.	DAMP HEAL, CYCLIC R 10
I	×		OF PARTS.	<del></del>	AT 40±2°C, HUMIDITY 90 TO 9	
I	×	CONTACT RESISTANCE: $100~\text{m}\Omega$ MAX. INSULATION RESISTANCE: $50~\text{M}\Omega$ MIN. NO DAMAGE, CRACK AND LOOSENESS	CONTACT RESISTANCE: INSULATION RESISTANC NO DAMAGE, CRACK AN	ω (Θ 🖯	$2 \times 5 \rightarrow 15 $	JRE OF
		OSION W	NO EVIDENCE AFFECTS TO CONNECTOR.	ω		
	>	ID LOOSE	NO DAMAGE, OF PARTS.	<b>№</b> (	96 h.	
١	<	SISTANCE: 100 mO MAX	CONTACT RESISTANCE:	⋽	CHARACTERISTICS	ENVIRONMENTAL CI
1	×	DIRECTION OF INSERTION: 0.15N × NUMBER OF CONTACTS MIN. (note 1)	DIRECTION OF 0.15N × NUMBE (note 1)	0. D	MEASURED BY APPLICABLE FPC. (THICKNESS OF FPC SHALL BE t=0.20mm AT INITIAL CONDITION.)	FPC RETENTION FORCE (TI
	×	SISTANCE: 100 mΩ MAX. CRACK AND LOOSENESS	유교		10 TIMES INSERTIONS AND EXTRACTIONS	MECHANICAL 10 OPERATION
	×	SISTANCE: 100 mΩ MAX. CRACK AND LOOSENESS	CONTACT RESISTANCE: NO DAMAGE, CRACK AN OF PARTS.	<u>@</u>	981 m/s², DURATION OF PULSE 6 ms AT 3 TIMES IN 3 DIRECTIONS.	SHOCK 981 n AT 3
	×	NO ELECTRICAL DISCONTINUITY OF 1 μs.	IO ELECTRIC s.	<u></u> ⊖	FREQUENCY 10 TO 55 Hz, HALF AMPLITUDE 0.75 mm, FOR 10 CYCLES IN 3 DIRECTIONS	ŌN
					ISTICS	VIICAL
>	<b>×</b>	BULK RESISTANCE	IDING FPC	(L=12)	,	
×	×		SO INISE ININ.	100	. MAY / AO:4 KH2	RESISTANCE CONTACT BESISTANCE
×	×	OX BXEARDOWN.			90 V AC FOR 1 min.	ŶÛÛF
					ERISTICS	HARA
×	×				CONFIRMED VISUALLY.	MARKING CC
×	×	DRAWING.	ACCORDING TO DRAWING		VISUALLY AND BY MEASURING INSTRUMENT.	z
ĄT	Q	REQUIREMENTS	RE		TEST METHOD	CONSTRUCTION
				ATIONS	SPECIFICATIONS	
G	LATIN	t=0.2±0.03mm, GOLD PLATING	E CABLE	APPLICABLE	0.2 A	CURRENT
:WED)	(NOT DE	RELATIVE HUMIDITY $90\%$ MAX (NOT DEWED)	OR STORAGE	OPERATING OF HUMIDITY RANGE	30 V AC / DC	RATING VOLTAGE
TION)	CONDI	-10°C TO 50°C (PACKED CONDITION)	ת ת	STORAGE TEMPERAT	-55 °C TO 85 °C	OPERATING TEMPERATURE RANGE
					RD	APPLICABLE STANDARD

)RM HD0011-2-

FORM HD0011-2-2

HIROSE ELECTRIC CO.

(note 1) THIS PRODI IF FORCE IN (note 2) BLISTERS V	
SOLDERABILITY  RESISTANCE TO SOLDERING HEAT	EXPOSED AT 40±2 °C, RELATIVE HUMIDITY 80±   32] 5%,   10 TO 15 ppm FOR 96 h.   SOLDERED AT SOLDER TEMPERATURE,   235 ±5°C FOR IMMERSION DURATION,   2±0.5 sec.   1) REFLOW SOLDERING:   PEAK TMP. 250 °C MAX.   REFLOW TMP. OVER 230 °C WITHIN 60 sec.   TIMP. 350 ± 10 °C FOR 5±1 sec.   (7)
SOLDERABILITY  RESISTANCE TO SOLDERING HEAT	5%, 10 TO 15 ppm FOR 96 h. SOLDERED AT SOLDER TEMPERATURE, 235 ±5°C FOR IMMERSION DURATION, 2±0.5 sec. 1) REFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec. 2) SOLDERING IRONS: TMP. 350 ± 10 °C FOR 5±1 sec.
HYDROGEN SULPHIDE [JIS C 003 SOLDERABILITY RESISTANCE TO SOLDERING HEAT	EXPOSED AT 40±2 °C, RELATIVE HUMIDITY 80± 22] 5%, 10 TO 15 ppm FOR 96 h. SOLDERED AT SOLDER TEMPERATURE, 235 ±5°C FOR IMMERSION DURATION, 2±0.5 sec. 1) REFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec. 2) SOLDERING IRONS: TMP. 350 ± 10 °C FOR 5±1 sec.
HYDROGEN SULPHIDE [JIS C 00] SOLDERABILITY RESISTANCE TO SOLDERING HEAT	25±5 ppm FOR 96 h.  EXPOSED AT 40±2 °C , RELATIVE HUMIDITY 80± 32] 5%,  10 TO 15 ppm FOR 96 h.  SOLDERED AT SOLDER TEMPERATURE, 235 ±5°C FOR IMMERSION DURATION, 2±0.5 sec.  1) REFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec. 2) SOLDERING IRONS: TMP. 350 ± 10 °C FOR 5±1 sec.
HYDROGEN SULPHIDE [JIS C 00] SOLDERABILITY RESISTANCE TO SOLDERING HEAT	EXPOSED AT 40±2 °C, RELATIVE HUMIDITY 80±  23] 5%,  10 TO 15 ppm FOR 96 h.  SOLDERED AT SOLDER TEMPERATURE,  235 ±5°C FOR IMMERSION DURATION,  2±0.5 sec.  1) REFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec.  2) SOLDERING IRONS:  TMP. 350 ± 10 °C FOR 5±1 sec.
HYDROGEN SULPHIDE [JIS C 00] SOLDERABILITY RESISTANCE TO SOLDERING HEAT	EXPOSED AT 40±2 °C, RELATIVE HUMIDITY 80±32] 5%, 10 TO 15 ppm FOR 96 h.  SOLDERED AT SOLDER TEMPERATURE, 235 ±5°C FOR IMMERSION DURATION, 2±0.5 sec. 1) REFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec. 2) SOLDERING IRONS: TMP. 350 ± 10 °C FOR 5±1 sec.
SOLDERABILITY  RESISTANCE TO SOLDERING HEAT	DERED AT SOLDER TEMPERATURE, ±5°C FOR IMMERSION DURATION, 5 sec. EFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec. OLDERING IRONS: MP. 350 ± 10 °C FOR 5±1 sec.
RESISTANCE TO SOLDERING HEAT	IIN 60 sec.
RESISTANCE TO SOLDERING HEAT	AX. R 230 °C WITHIN 60 sec. FOR 5±1 sec.
	350 ± 10 °C FOR
(note 1)	
IF FORCE IN	ote 1) THIS PRODUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC ON PCB
(note 2)	
BLISTERS V	1 FPC
	OT PR
	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC O IN VERTICAL DIRECTION SHALL BE PREDICTED. WHICH MAY OCCUR IN HOUSING DO NOT AFFECT PRO
	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC O IN VERTICAL DIRECTION SHALL BE PREDICTED. WHICH MAY OCCUR IN HOUSING DO NOT AFFECT PRO
	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC O IN VERTICAL DIRECTION SHALL BE PREDICTED. WHICH MAY OCCUR IN HOUSING DO NOT AFFECT PRO
	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC O IN VERTICAL DIRECTION SHALL BE PREDICTED.
	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC O IN VERTICAL DIRECTION SHALL BE PREDICTED.
Note QT:Qualification	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC ON PIN VERTICAL DIRECTION SHALL BE PREDICTED.  WHICH MAY OCCUR IN HOUSING DO NOT AFFECT PRODU
QT:Qualification	DUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC O IN VERTICAL DIRECTION SHALL BE PREDICTED.  WHICH MAY OCCUR IN HOUSING DO NOT AFFECT PRO  **Test AT:Assurance Test X:Applicable Test   DRAWING SPECIFICATION SHEET   PART NO.